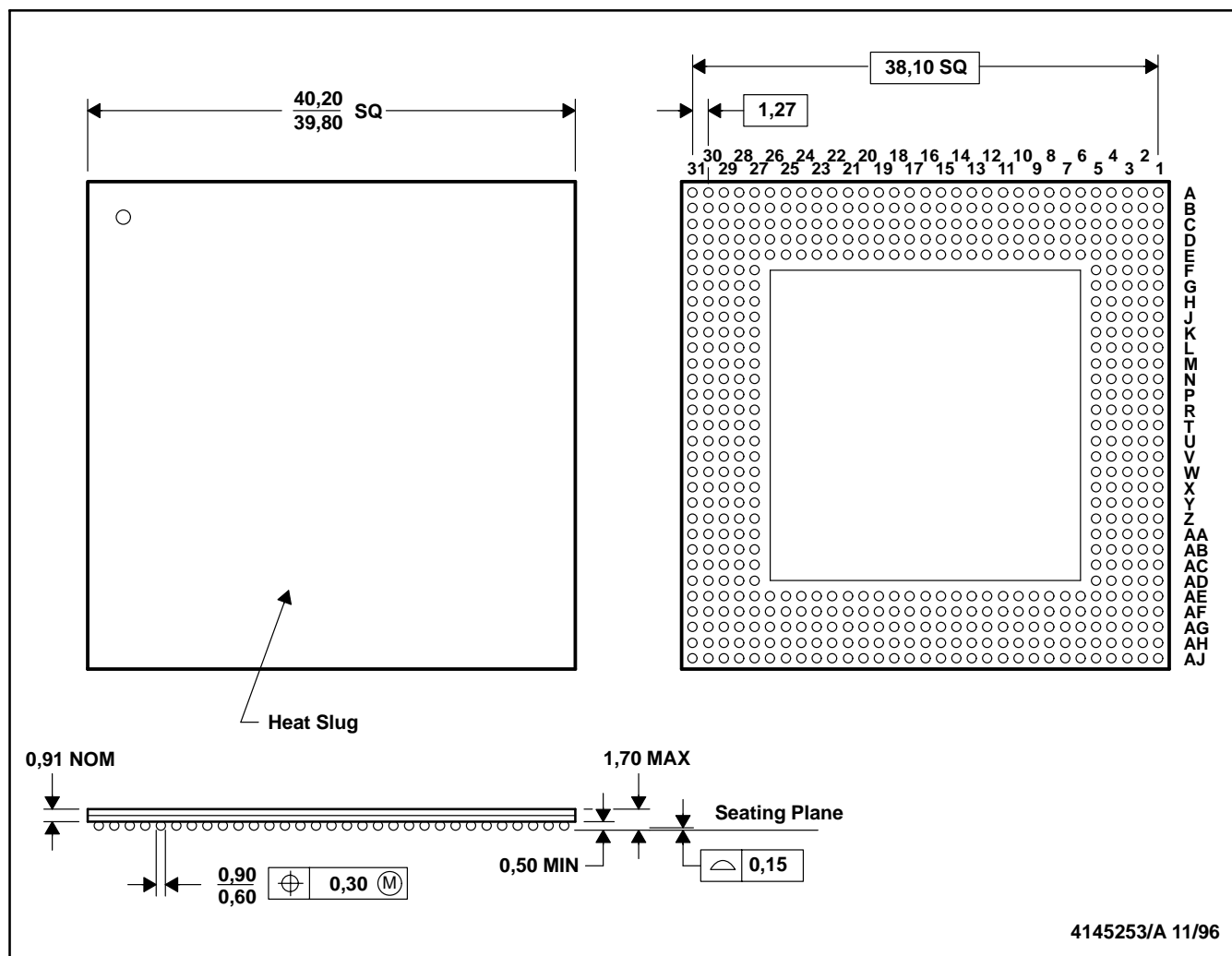


GGR (S-PBGA-N520)

PLASTIC BALL GRID ARRAY (CAVITY-DOWN) PACKAGE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Thermally enhanced die down plastic package with top surface metal heat slug.

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